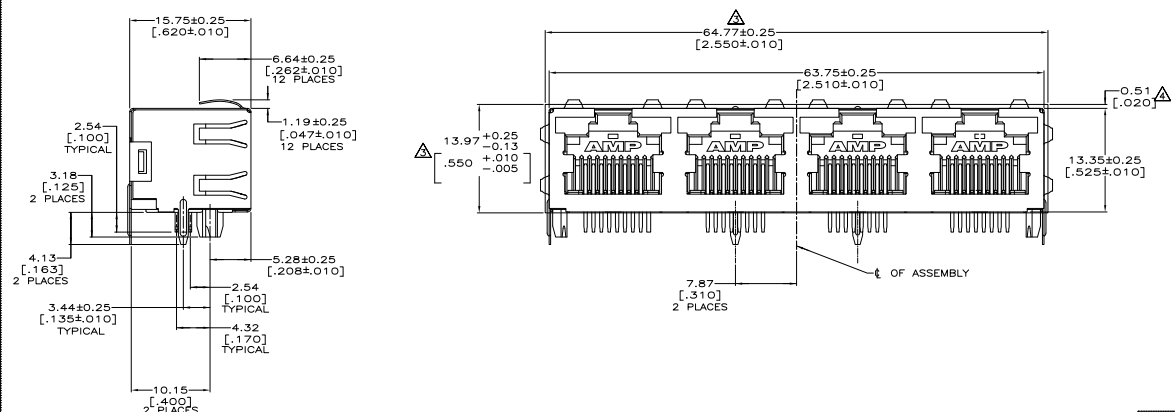


SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

- △ MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.
 SHIELD - .196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 2.03µm[.000080] - 3.81µm [.000150] BRIGHT TIN OVER 1.27µm [.000050] THICK MIN NICKEL.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.



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AA	22						
B				REV PER ECR-10-018314			

INVENTOR	DESIGNED BY	DRAWN BY	CHECKED BY	DATE

T&R	5406544-2
TRAY	5406544-1
PACKAGE	PART NUMBER

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